FULLY AUTOMATIC SINGLE SPINDLE DICING SAWS

7222

2″ Spindle

8″ silicon wafer dicing saw or other material such as PZT, IR glass and more

Features & Benefits

- Efficient wafer handling system
- Continuous digital magnifications vision system
- Blade wear prediction algorithm reduces height measurement time and increases UPH
- Atomized wafer cleaning technology for superior process results

Workpiece Size		Ø 8″
Spindle		60K rpm / 1.8 kW or 2.2KW
Blade Size		2″ – 3″
Y Axis	Control Resolution Cumulative Accuracy Indexing Accuracy	Linear encoder 0.1 μm 1.5 μm 1.0 μm
X Axis		Air Slide
Z Axis	Resolution Repeatability	0.2 μm 1.0 μm
Θ Axis	Repeatability Stroke	4 arc-sec 380°
Cleaning Station	 Spinning speed Cleaning Method	Full rinse and dry cycle 100-2,000 rpm Atomized cleaning capabilities
Utilities	Electrical	200-240 VAC, 50/60 Hz, single phase
Dimensions	(W x D x H) mm Weight	965 X 1460 X 1700 1,200kg

Materials:

Silicon | Glass on Silicon | MEMS | GaAs wafers | Package Singulation (BGA & QFN) | LTCC | PCB | Hard Materials

7302

2″ Spindle

For silicon / glass wafers

Features & Benefits

- Internal air flow managment management minimizing product contamination
- Multi panel dicing
- 'X' axis air bearing for smooth motion and super cut quality
- Automation with high resolution optics
- Custom process solution
- UV LED curing system
- Broken Blade detector (for 2″ spindle)
- Exhaust impeller
- High power 2″ spindle up to 2.2KW
- Height Measuring Tool (HMT)
- SECS GEM communication protocol

Workpiece Size		Ø 12″ or 9" X 12"
Spindle		60K rpm / 1.8 kW or 2.2KW
Blade Size		2" - 3"
Y Axis	Control Resolution Cumulative Accuracy Indexing Accuracy Cutting Range	Linear encoder 0.1 μm 1.5 μm 1.0 μm 350 mm
X Axis		Air Slide
Z Axis	Resolution Repeatability Max. Stroke	0.2 μm 1.0 μm 50 mm (for 2.188″ blade OD)
Θ Axis	Repeatability Stroke	4 arc-sec 380°
Cleaning Station	 Spinning speed Cleaning Method	Full rinse and dry cycle 100-2,000 rpm Atomized cleaning capabilities
Utilities	Electrical	200-240 VAC, 50/60 Hz, single phase
Dimensions	(W x D x H) mm Weight	1100 x 1785 x 1700 1,350kg

Materials:

Silicon Wafers | PCB | QFN and BGA multi panels | LED Packages